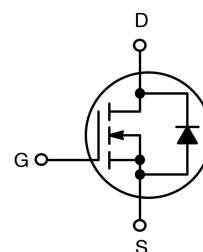
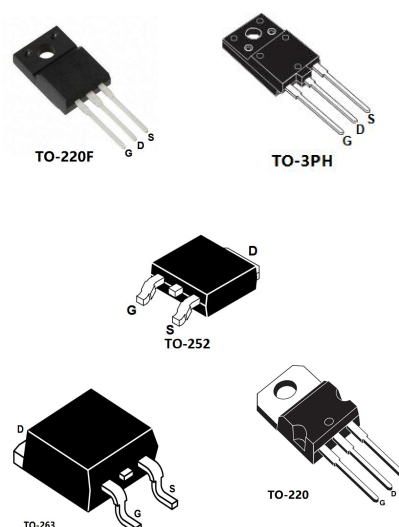


N-channel 1000V – 3.5Ω 5A

General features

| Type | VDSS(@Tjmax) | RDS(on) | ID |
|----------|--------------|---------|----|
| SL5N100P | 1000 V | < 4.2 Ω | 5A |
| SL5N100F | 1000 V | < 4.2 Ω | 5A |
| SL5N100 | 1000 V | < 4.2 Ω | 5A |
| SL5N100K | 1000 V | < 4.2 Ω | 5A |
| SL5N100D | 1000 V | < 4.2 Ω | 5A |

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatability



Applications

- Switching application

Order codes

| Partnumber | Package |
|------------|--------------|
| SL5N100P | TO-3PH |
| SL5N100F | TO-220F |
| SL5N100 | TO-220 |
| SL5N100K | TO-263/D2PAK |
| SL5N100D | TO-252/DPAK |

Electrical ratings

Absolute maximum ratings

| Parameter | Symbol | Value | | | | Unit |
|---|----------|--------|---------|-------------------|--------|------|
| | | TO-3PH | TO-220F | TO-220/ TO-252 | TO-263 | |
| Drain-source voltage ($V_{GS}=0$) | V_{DS} | 1000 | | | | V |
| Gate-source voltage | V_{GS} | ±30 | | | | |
| Drain current (continuous) at $TC=25^{\circ}C$ | I_D | 5 | | | | A |
| Drain current (continuous) at $TC=100^{\circ}C$ | I_D | 3 | | | | |
| Drain current (pulsed) | I_{DM} | 18 | 18 | 18 | 18 | |
| Total dissipation at $TC=25^{\circ}C$ | PTOT | 48 | 60 | 60 | 80 | W |

| | | | |
|---|---------------|------------|------|
| Drain source ESD (HBM-C=100pF,R=1.5KΩ) | $V_{ESD(GS)}$ | 4000 | V |
| Peak diode recovery voltage slope | dv/dt | 4.5 | V/ns |
| Insulation withstand voltage(RMS)from all three leads to external heat sink (t=1s TC=25°C) | V_{ISO} | 2500 | v |
| Operating junction temperature | T_J | -55 to 175 | °C |
| Storage temperature | T_{STG} | | |

Thermal data

| Parameter | Symbol | Value | | | | Unit |
|---|-----------|---------|--------|-------------------|--------|------|
| | | TO-220F | TO-3PH | TO-220/ TO-252 | TO-263 | |
| Thermal resistance junction max | Rthj-case | 4.2 | 2.6 | 4.2 | 0.63 | °C/W |
| Thermal resistance junction-ambient max | Rtha-case | 68 | 58 | 68 | 35 | °C/W |
| Maximum lead temperature for soldering purpose | T | 350 | | | | mJ |

Avalanche characteristics

| Parameter | Symbol | Value | Unit |
|---|--------|-------|------|
| Avalanche current repetitive or not-repetitive (pulse width limited by Tj Max) | IAR | 5 | A |
| Single pulse avalanche energy (starting Tj=25°C Id=Iar Vdd=50V) | EAS | 583 | mJ |

Electrical characteristics (T_{CASE}=25°C unless otherwise specified)
On/off states

| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|--|--------------|----------------------|------|-----|-----|------|
| Drain-source breakdown voltage | $V_{(BR)DS}$ | ID=1mA VGS=0 | 1000 | | | V |
| Zero gate voltage drain current (VGS=0) | IDSS | VDS=Max rating | | | 1 | μA |
| | | TC=125°C | | | 50 | μA |
| Gate body leakage current (VGS=0) | IGSS | VGS=±20V | | | ±10 | μA |
| Gate threshold voltage | $V_{GS(th)}$ | VDS=VGS ID=100 μA | 3 | 3.5 | 4.5 | V |

| | | | | | | |
|-----------------------------------|---------------------|--|--|-----|-----|---|
| Static drain-source on resistance | R _{DS(on)} | V _{GS} =10V I _D =1.75A | | 3.5 | 4.2 | Ω |
|-----------------------------------|---------------------|--|--|-----|-----|---|

Dynamic

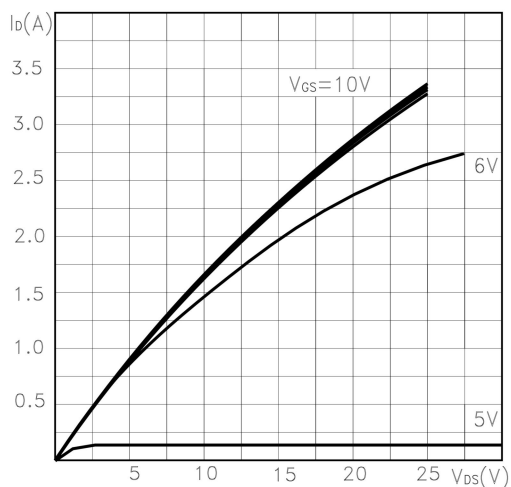
| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------|---|-----|-------|-----|------|
| Forward transconductance | g _{fs} | V _{DS} = 40 V, I _D = 4A | | 5 | | S |
| Input capacitance | C _{iss} | V _{DS} =25V, f=1MHz, V _{GS} =0 | | 483 | | pF |
| Output capacitance | C _{oss} | | | 45 | | |
| Reverse transfer capacitance | C _{rss} | | | 9 | | |
| Equivalent Output capacitance | C _{oss eq.} | V _{GS} =0, V _{DS} =0 to 800V | | 46.8 | | |
| Gate input resistance | R _g | f=1MHz Gate DC Bias=0 Test signal level=20mV open drain | | 3.65 | | Ω |
| Total gate charge | Q _g | V _{DD} =750V, I _D =4A V _{GS} =10V | | 12.67 | | nC |
| Gate-source charge | Q _{gs} | | | 3.7 | | |
| Gate-drain charge | Q _{gd} | | | 4.23 | | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 500 V, I _D = 1.75 A, R _G = 4.7 Ω, V _{GS} = 10 V | | 11.3 | | ns |
| Rise time | t _r | | | 18.5 | | |
| Turn-off-delay time | t _{d(off)} | | | 55 | | |
| Fall time | t _f | | | 17 | | |

Source Drain Diode

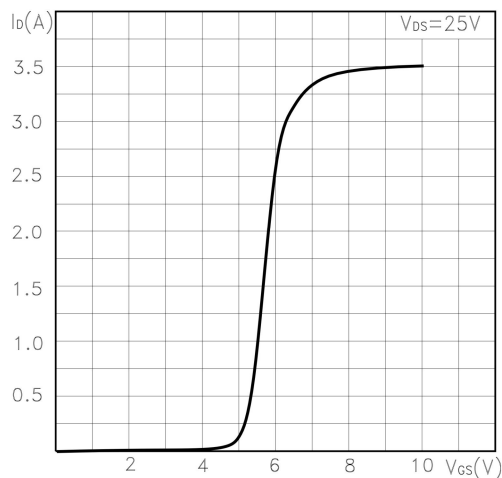
| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|------------------------------|------------------|---|-----|------|-----|------|
| Source Drain Current | I _{SD} | | | | 5 | A |
| Source Drain Current(Pulsed) | I _{SDM} | | | | 20 | A |
| Forward On Voltage | V _{SD} | I _{SD} =5A, V _{GS} =0V | | | 1.2 | V |
| Reverse Recovery Time | T _{rr} | I _{SD} =4A, di/dt=100A/μS | | 154 | | ns |
| Reverse Recovery Charge | Q _{rr} | V _R =100V, T _j =150°C | | 677 | | nC |
| Reverse Recovery Current | I _{RRM} | | | 5.23 | | A |

Electrical characteristics (curves)

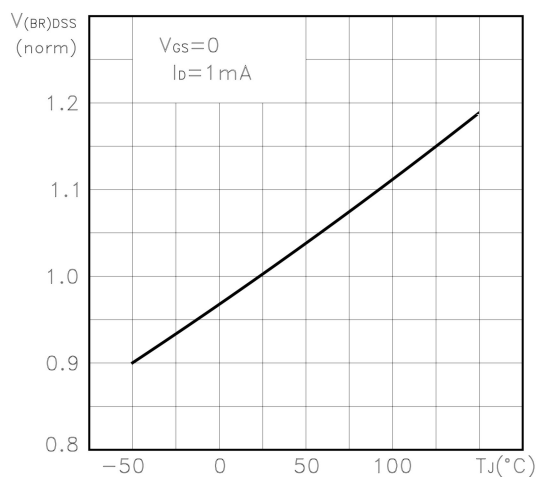
Output characteristics



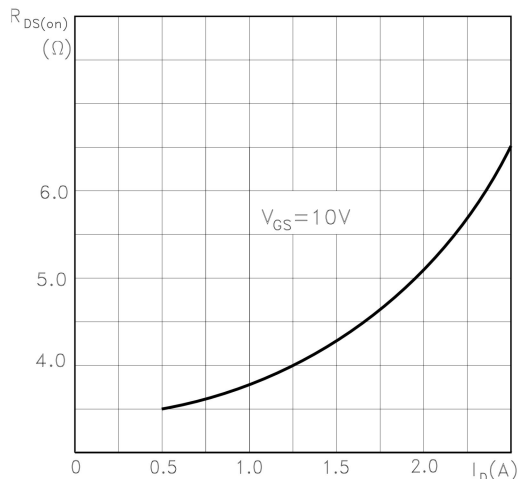
Transfer characteristics



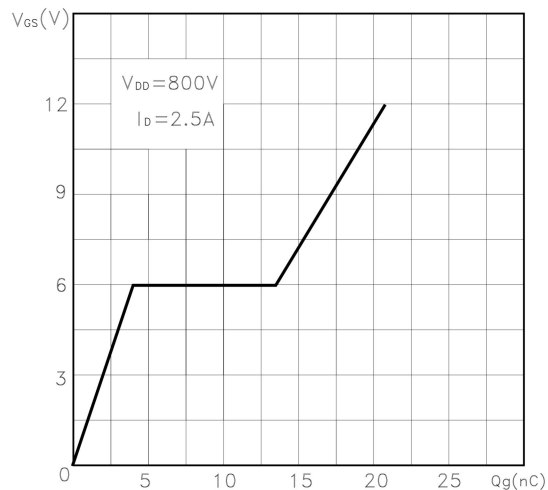
Normalized BV_{DSS} vs. temperature



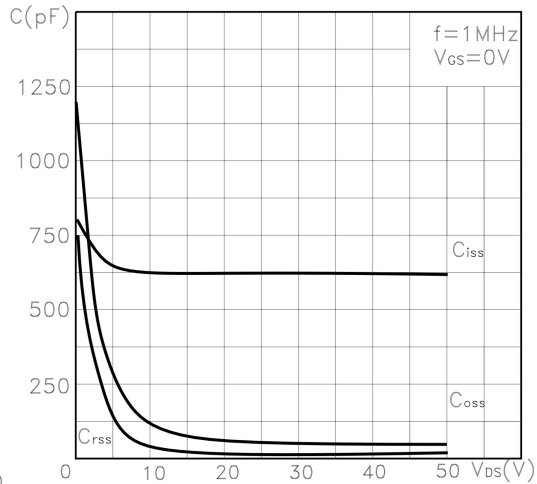
Static drain-source on resistance



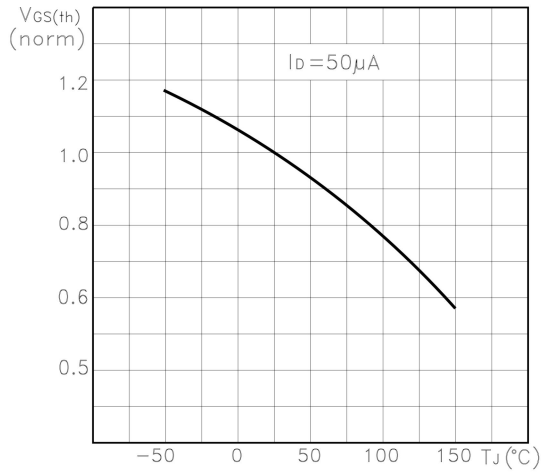
Gate charge vs. gate-source voltage



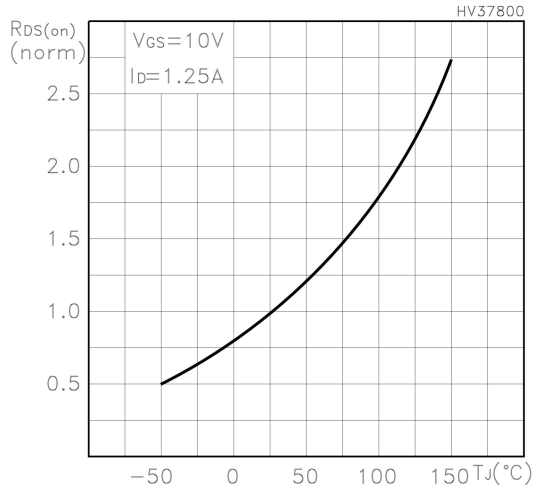
Capacitance variations



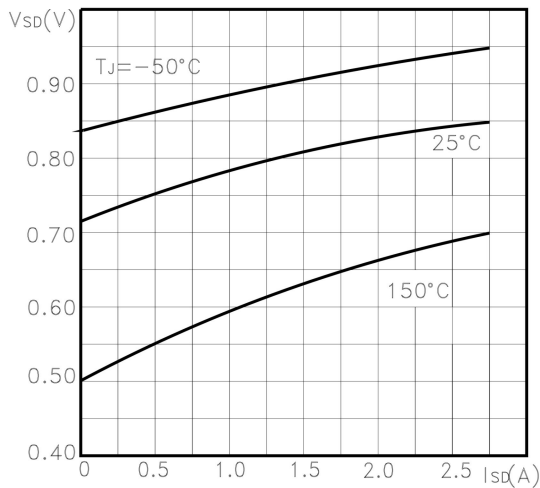
Normalized gate threshold voltage vs. temperature



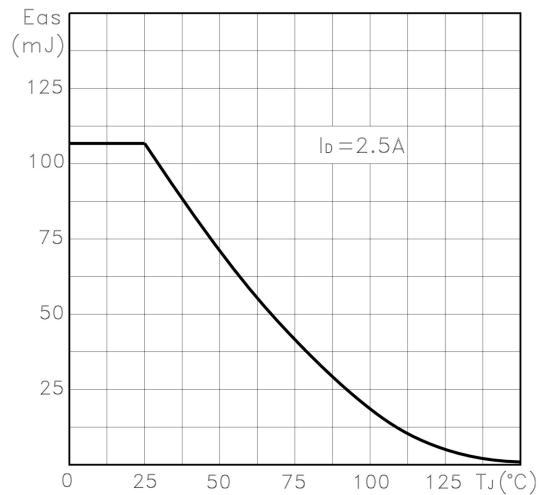
Normalized on resistance vs. temperature



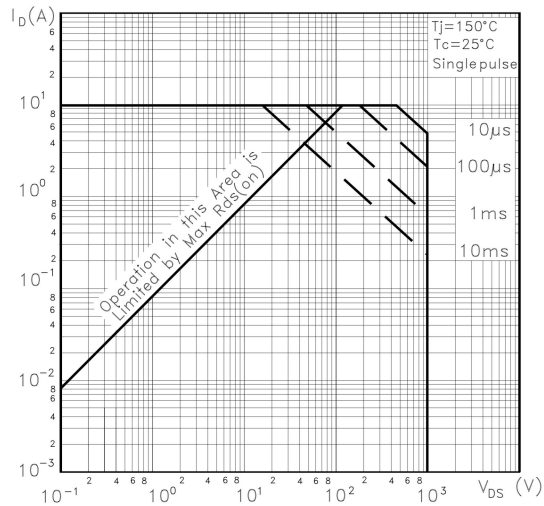
Source-drain diode forward characteristics



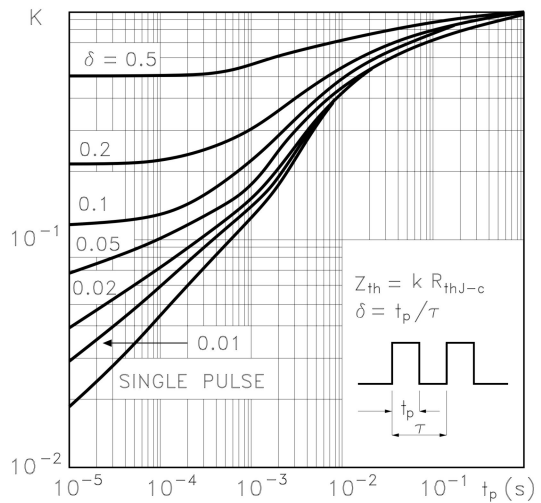
Maximum avalanche energy vs Tj



Safe operating area

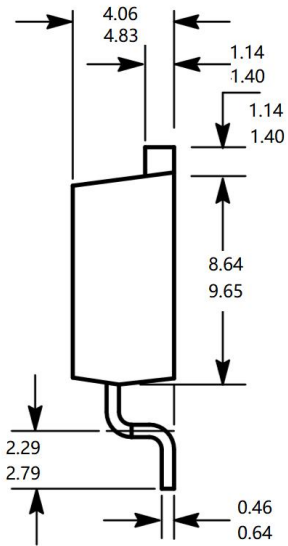
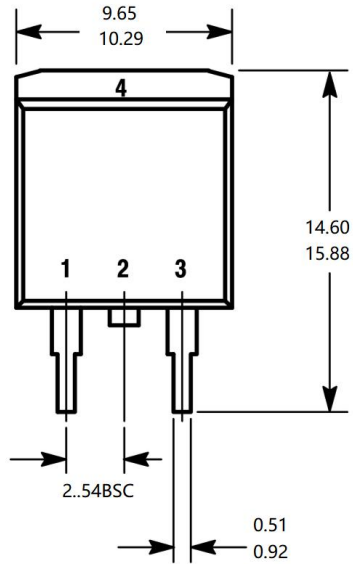


Thermal impedance

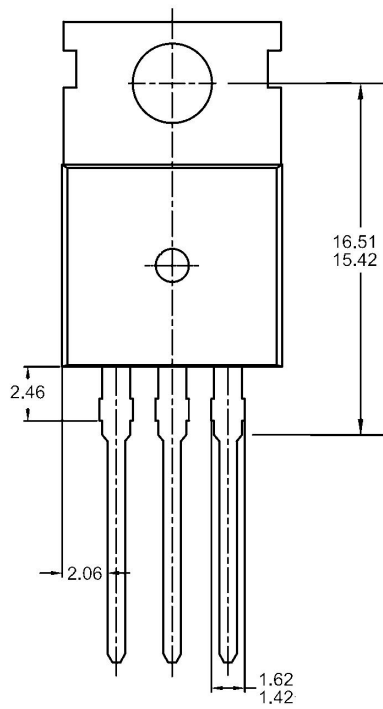


Package outline dimension

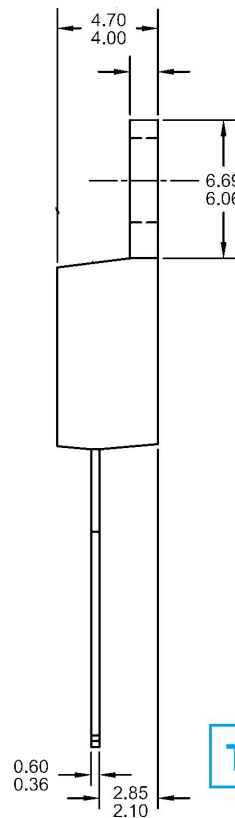
TO-263/D2PAK



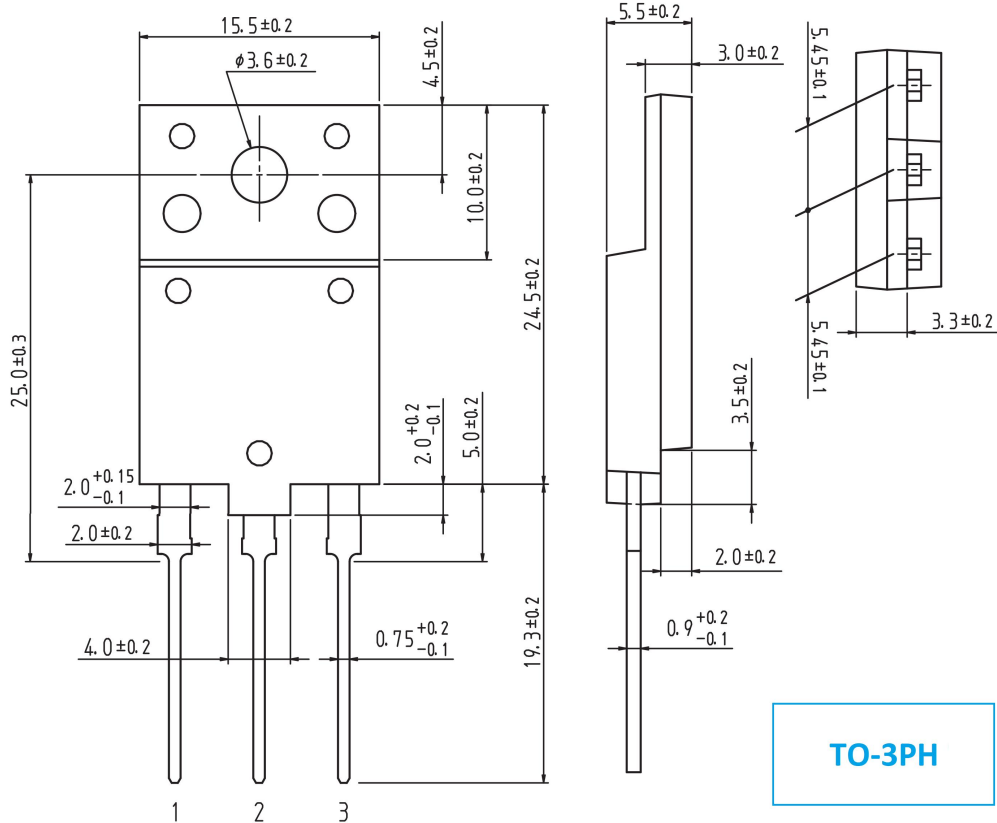
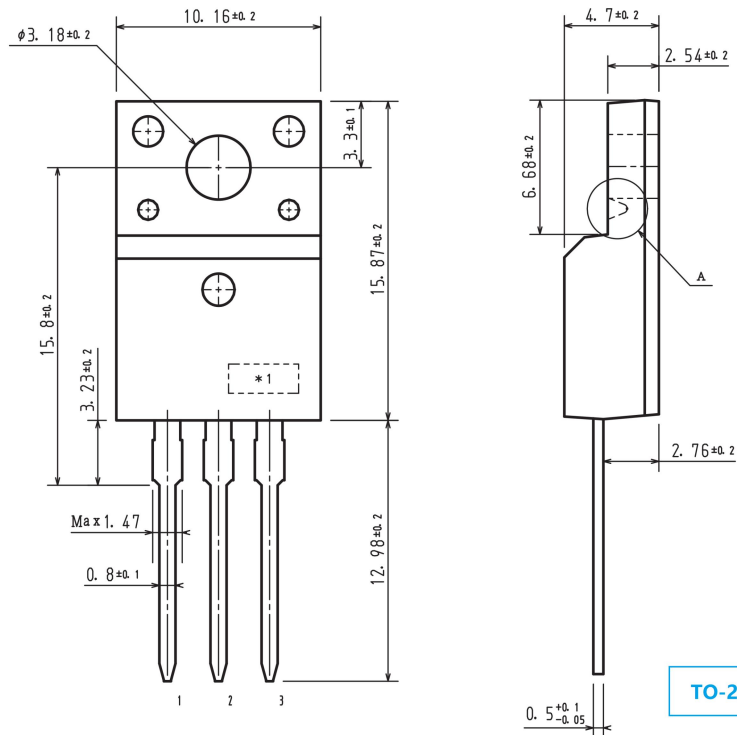
TO-263/D2PAK

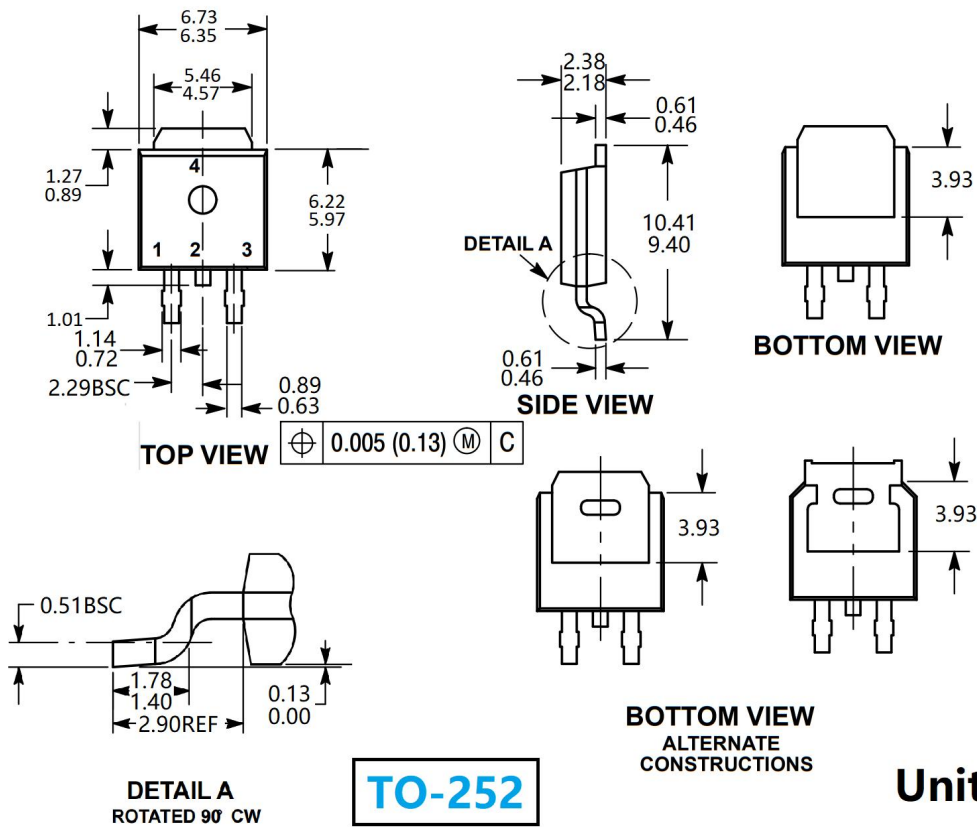


TO-220



TO-220





Unit:mm